

PCN Number:	20160323000		PCN Date:	03/23/2016
Title:	Carrier Tape Change for INA216A1YFF Device			
Customer Contact:	PCN Manager	Dept:	Quality Services	
Proposed 1st Ship Date:	06/23/2016			
Change Type:				
☐ Assembly Site	☐ Assembly Process	☐ Assembly Materials		
☐ Design	☐ Electrical Specification	☐ Mechanical Specification		
☐ Test Site	☒ Packing/Shipping/Labeling	☐ Test Process		
☐ Wafer Bump Site	☐ Wafer Bump Material	☐ Wafer Bump Process		
☐ Wafer Fab Site	☐ Wafer Fab Materials	☐ Wafer Fab Process		
☐ Part number change				

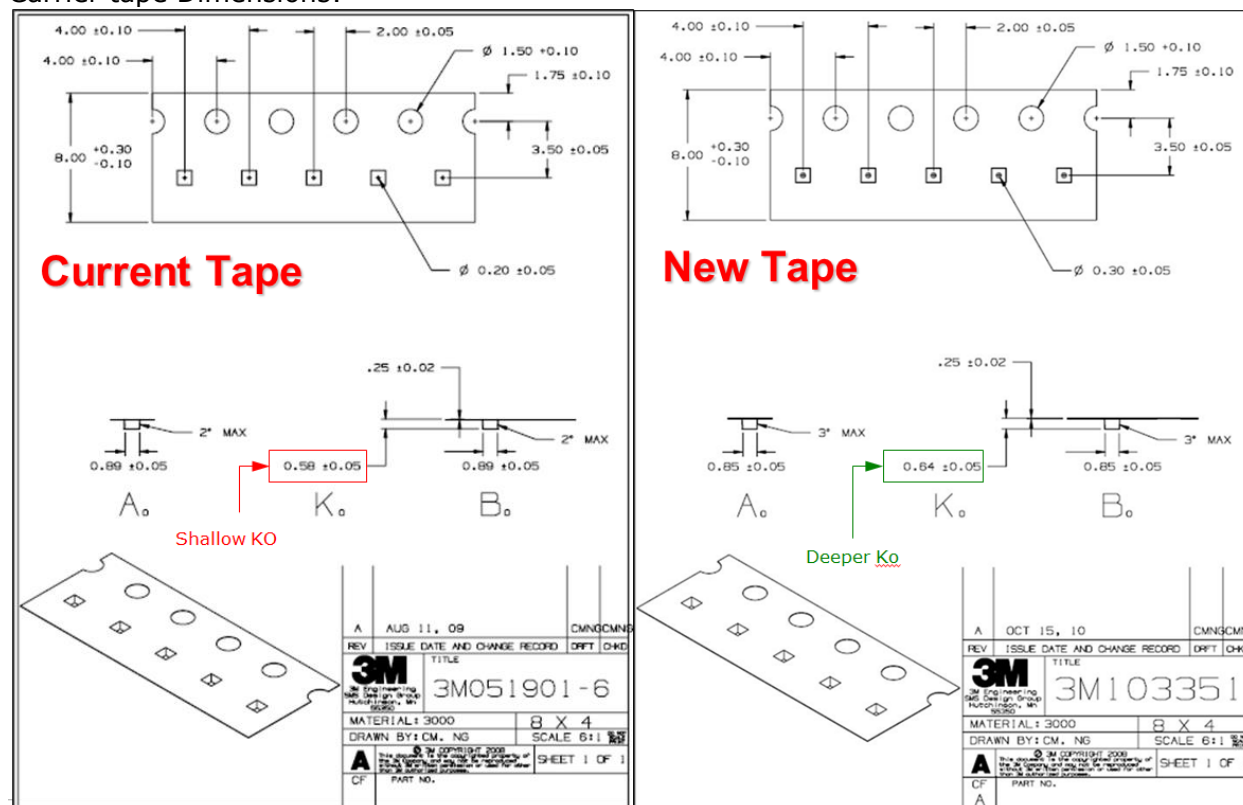
PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new carrier tape for the INA216A1YFF device. The material composition between the 2 carrier tapes is the same. A dimensional comparison summary is below:

Dimension	From	To
Ao	0.89 (+/- 0.05) mm	0.85 (+/- 0.05) mm
Bo	0.89 (+/- 0.05) mm	0.85 (+/- 0.05) mm
Ko	0.58 (+/- 0.05) mm	0.64 (+/- 0.05) mm

Carrier tape Dimensions:



Reason for Change:	
Standardization	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):	
None	
Changes to product identification resulting from this PCN:	
New Carrier Tape	
Product Affected:	
INA216A1YFFR	INA216A1YFFT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com